

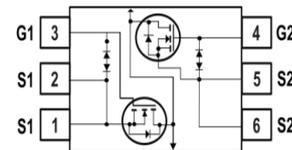
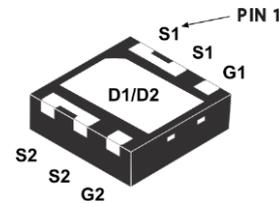
➤ General Description

This PAN82TE36S Dual N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent $R_{ds(On)}$ performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➤ Feature

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- ESD Protected
- Advanced high cell density Trench technology
- DFN2X2A-EP3 package design

➤ DFN2X2A-EP3



➤ Application

- Load Switch
- Portable Equipment
- Battery Powered System

➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ¹	$I_D@T_A=25^\circ C$	6	A
Continuous Drain Current ¹	$I_D@T_A=70^\circ C$	4.8	A
Pulsed Drain Current ²	I_{DM}	36	A
Total Power Dissipation ³	$P_D@T_A=25^\circ C$	1.4	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ C$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ C$
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	90	$^\circ C/W$

➤ Electrical Characteristics ($T_J=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	---	---	V
Static Drain-Source On-Resistance ²	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=3.0A$	14.0	17.5	22.0	m Ω
		$V_{GS}=4.0V, I_D=3.0A$	14.5	18.0	22.5	
		$V_{GS}=3.7V, I_D=3.0A$	15.0	18.5	23.0	
		$V_{GS}=3.1V, I_D=3.0A$	15.5	19.5	25.0	
		$V_{GS}=2.5V, I_D=3.0A$	17.5	22.0	29	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.5	0.7	1.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=16V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	uA
		$V_{DS}=16V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 8V, V_{DS}=0V$	---	---	± 10	uA
Forward Transconductance	g_{fs}	$V_{DS}=5V, I_D=3.0A$	---	20	---	S
Total Gate Charge	Q_g	$V_{DS}=15V, V_{GS}=4.5V, I_D=6A$	---	10.4	---	nC
Gate-Source Charge	Q_{gs}		---	1.3	---	
Gate-Drain Charge	Q_{gd}		---	2.6	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=10V, V_{GS}=4.5V, R_G=3.3\Omega$ $I_D=3A$	---	3.2	---	ns
Rise Time	T_r		---	9.8	---	
Turn-Off Delay Time	$T_{d(off)}$		---	31	---	
Fall Time	T_f		---	3.6	---	
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	630	---	pF
Output Capacitance	C_{oss}		---	66	---	
Reverse Transfer Capacitance	C_{rss}		---	63	---	

➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current ^{1,4}	I_S	$V_G=V_D=0V$, Force Current	---	---	6	A
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	0.86	1.2	V

Note :

1. Pulse width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. Ensure that the channel temperature does not exceed $150^\circ C$.
4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

➤ Typical Characteristics

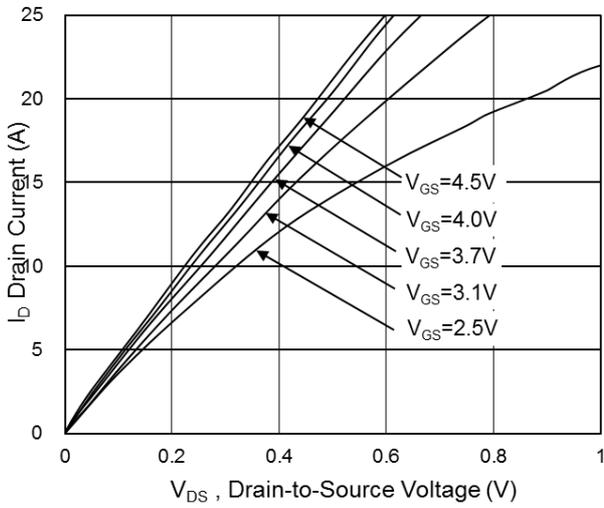


Fig.1 Typical Output Characteristics

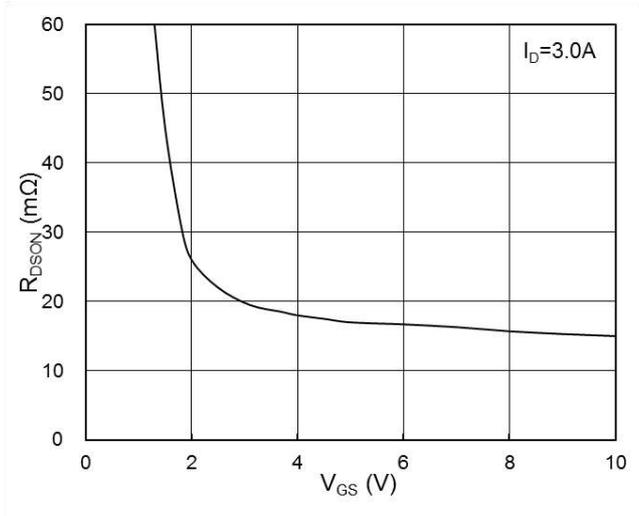


Fig.2 On-Resistance vs. Gate-Source voltage

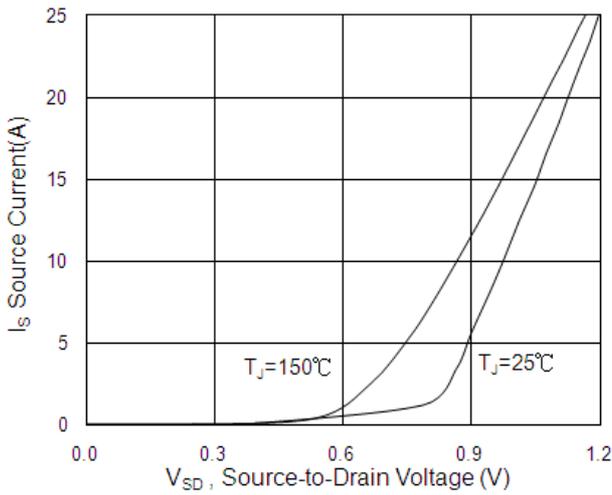


Fig.3 Forward Characteristics Of Reverse

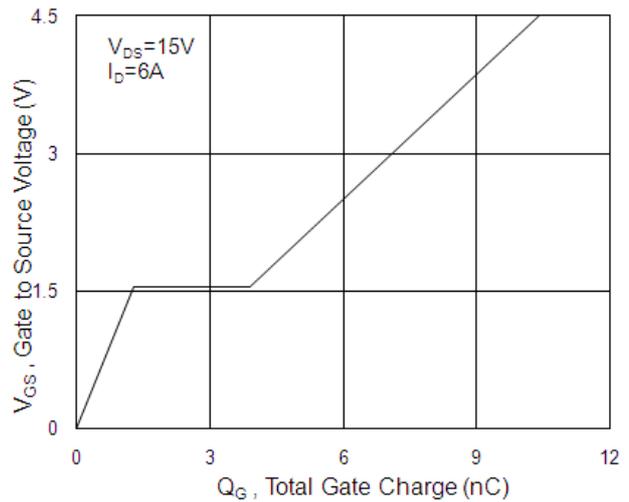


Fig.4 Gate-Charge Characteristics

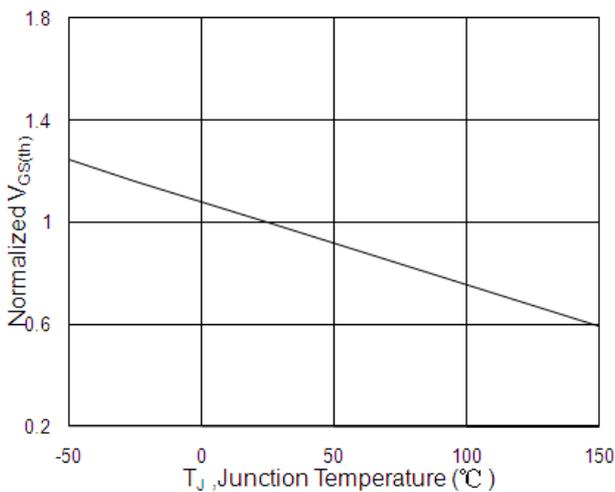


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

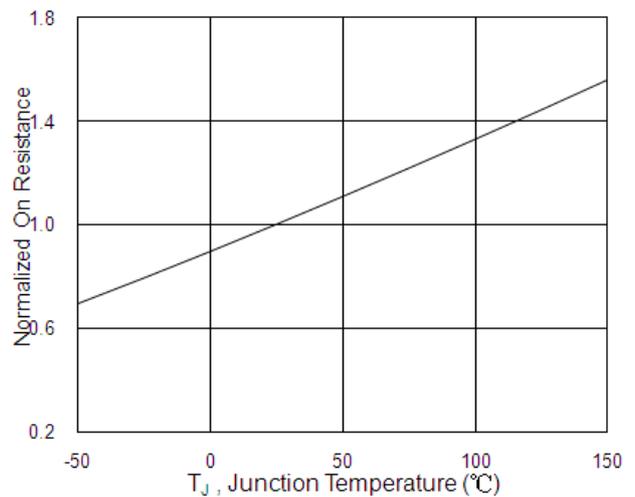


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

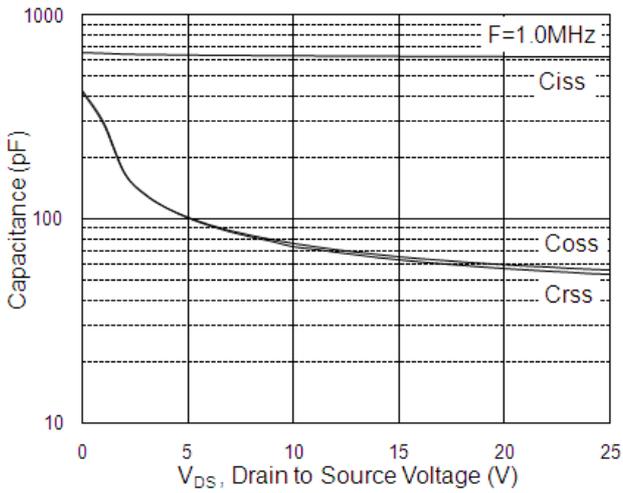


Fig.7 Capacitance

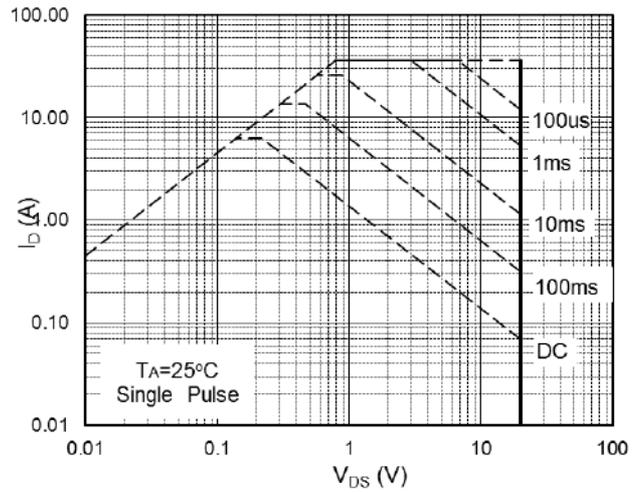


Fig.8 Safe Operating Area

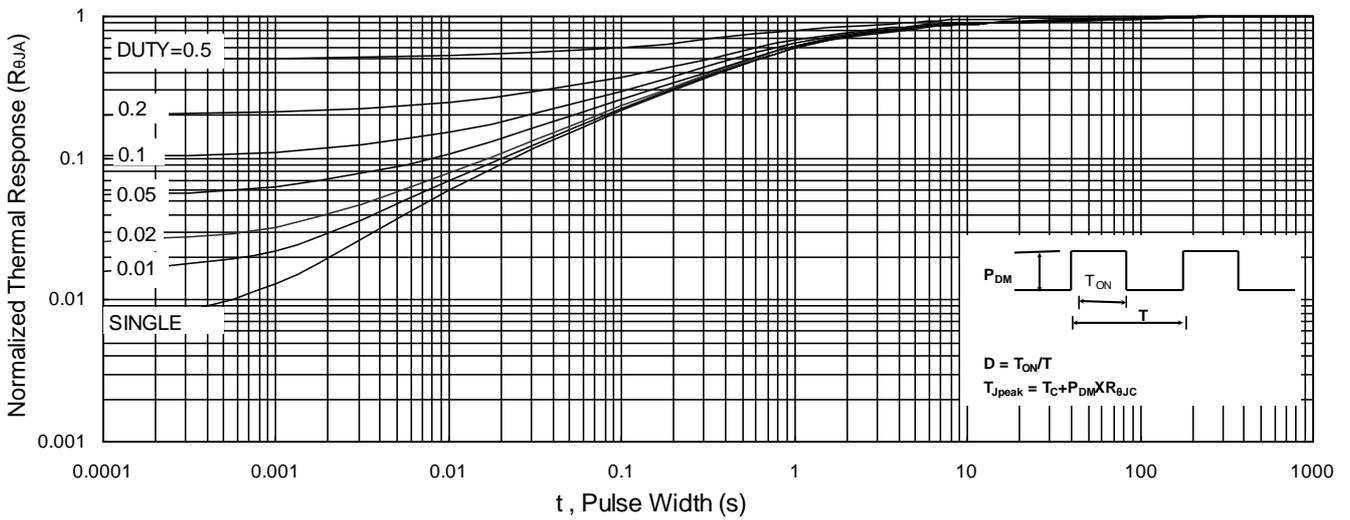


Fig.9 Normalized Maximum Transient Thermal Impedance

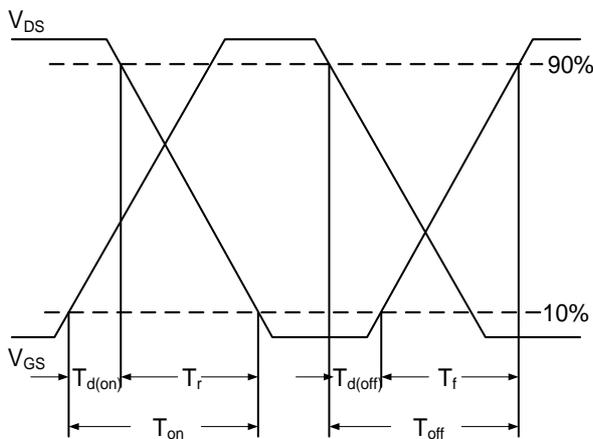


Fig.10 Switching Time Waveform

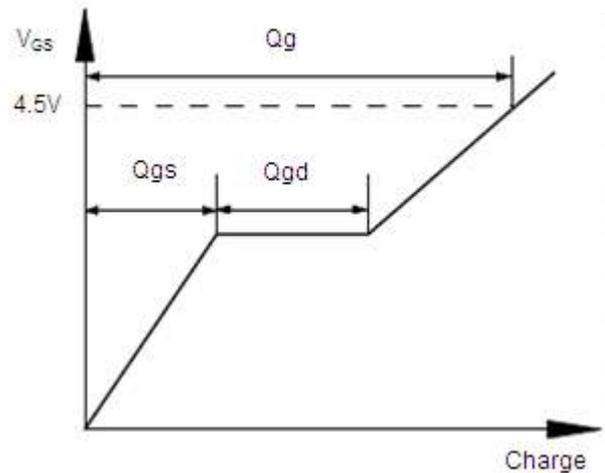
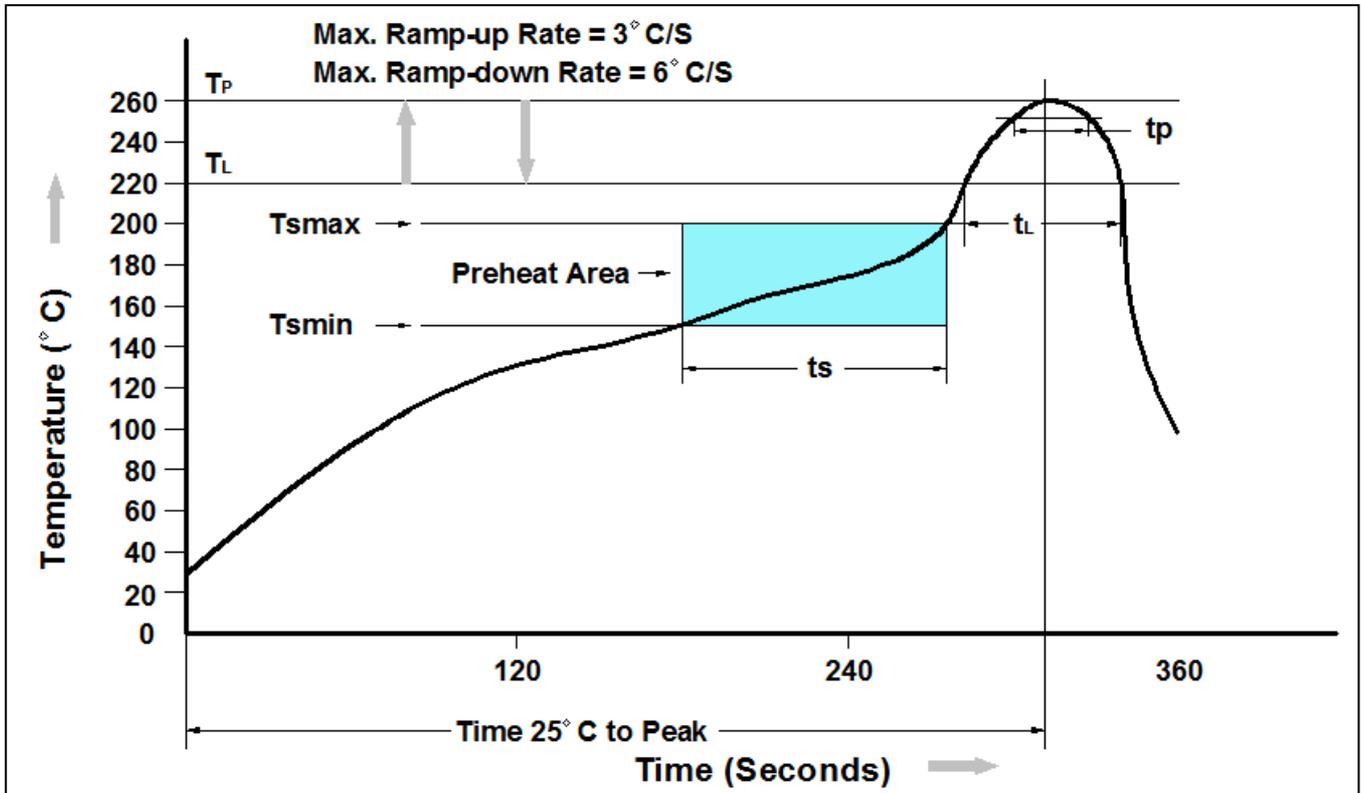


Fig.11 Gate Charge Waveform

➤ Recommnd IR Reflow Soldering Thermal Profile

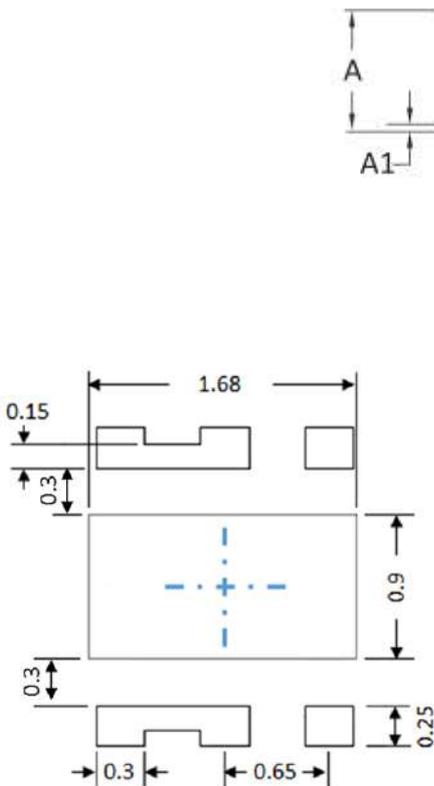
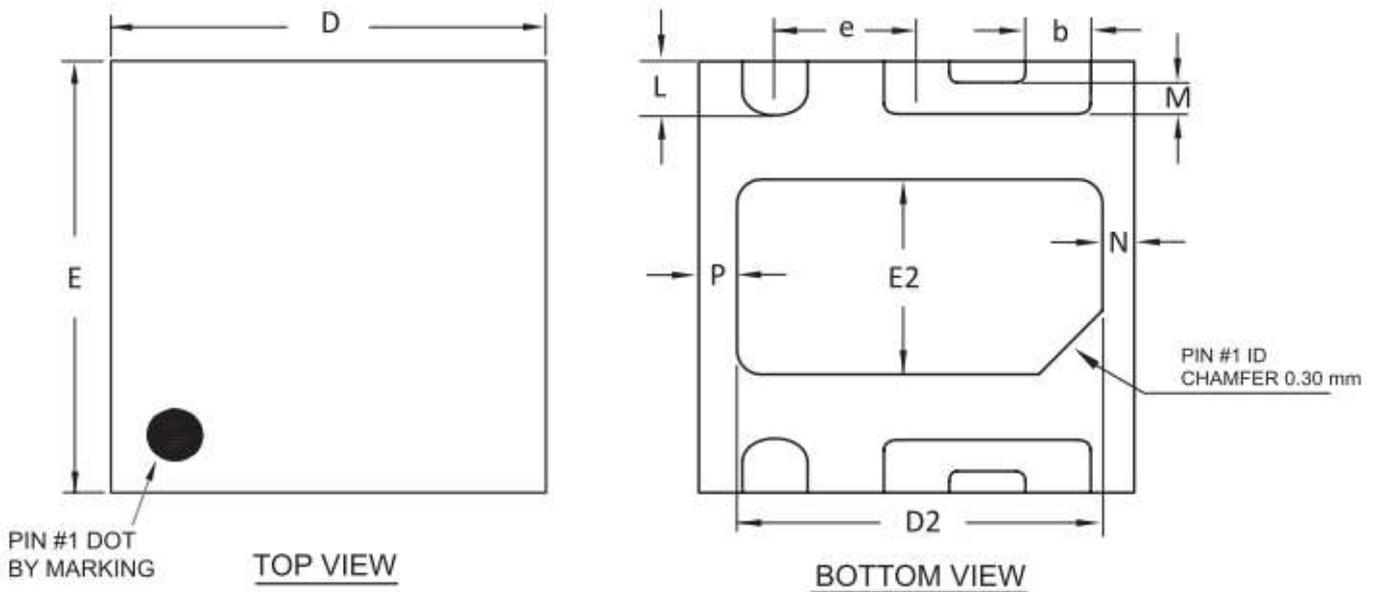


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Average Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ Ordering Information

Part Number	Description	Quantity
PAN82TE36S	DFN2X2A-EP3 Reel	3000 pcs

➤ Package Information (DFN2X2A-EP3)



Recommended Land Pattern

SYMBOLS	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	0.550	0.600	—	0.022	0.024
A1	0.000	—	0.050	0.000	—	0.002
A3	0.150 BSC			0.006 BSC		
D	1.950	2.000	2.050	0.077	0.079	0.081
E	1.950	2.000	2.050	0.077	0.079	0.081
D2	1.625	1.675	1.725	0.064	0.066	0.068
E2	0.850	0.900	0.950	0.033	0.035	0.037
L	0.250 BSC			0.010 BSC		
b	0.250	0.300	0.350	0.010	0.012	0.014
e	0.650 BSC			0.026 BSC		
M	0.150 BSC			0.006 BSC		
N	0.150 BSC			0.006 BSC		
P	0.175 BSC			0.007 BSC		

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